

L Number	Hits	Search Text	DB	Time stamp
1	22783	((conducitve adj paste) or paste or (paste adj material)) same advan\$4	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/14 19:21
2	2103	((conducitve adj paste) or paste or (paste adj material)) same advan\$4) and (carrier or (carrier adj board))	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/14 19:56
3	1227	((conducitve adj paste) or paste or (paste adj material)) same advan\$4) and (carrier or (carrier adj board))) and (component or die or chip or IC)	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/14 17:56
4	131	((conducitve adj paste) or paste or (paste adj material)) same advan\$4) and (carrier or (carrier adj board))) and (component or die or chip or IC)) and (PCB or (circuit adj board))	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/14 17:57
5	119	((conducitve adj paste) or paste or (paste adj material)) same advan\$4) and (carrier or (carrier adj board))) and (component or die or chip or IC)) and (PCB or (circuit adj board))) and (solder or (solder adj ball) or (solder adj bump))	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/14 18:14
6	41	((conducitve adj paste) or paste or (paste adj material)) same advan\$4) and (carrier or (carrier adj board))) and (component or die or chip or IC)) and (PCB or (circuit adj board))) and (solder or (solder adj ball) or (solder adj bump))) and (melting adj point)	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/14 18:15
7	1346	174/250-268.ccls. and ((conducitve adj paste) or paste or (paste adj material))	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/14 18:14
8	930	(174/250-268.ccls. and ((conducitve adj paste) or paste or (paste adj material))) and (solder or (solder adj ball) or (solder adj bump))	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/14 18:14
9	244	((174/250-268.ccls. and ((conducitve adj paste) or paste or (paste adj material))) and (solder or (solder adj ball) or (solder adj bump))) and (melting adj point)	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/14 18:33
10	230	paste same (high\$3 adj melting adj point) same solder	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/14 18:35
11	26	361/\$.ccls. and (paste same (high\$3 adj melting adj point) same solder)	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/14 18:39
12	0	174/250-268/\$.ccls. and (paste same (high\$3 adj melting adj point) same solder)	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/14 18:40
13	0	257/600-800/\$.ccls. and (paste same (high\$3 adj melting adj point) same solder)	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/14 18:40
15	21	174/250-268.ccls. and (paste same (high\$3 adj melting adj point) same solder)	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/14 18:42
14	45	257/600-780.ccls. and (paste same (high\$3 adj melting adj point) same solder)	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/14 18:42

16	0	((conducitve adj paste) same (melting adj point))	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/14 19:54
17	6054	paste same (melting adj point)	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/14 19:56
18	940	paste same (melting adj point) same solder	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/14 19:56
19	546	(paste same (melting adj point) same solder) and (carrier or (carrier adj board) or board)	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/14 19:57
20	124	paste same (high adj melting adj point) same solder	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/14 20:22
21	88	(paste same (high adj melting adj point) same solder) and (carrier or (carrier adj board) or board)	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/14 19:57
22	0	(paste adj material) same (high adj melting adj point) same solder	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/14 20:23